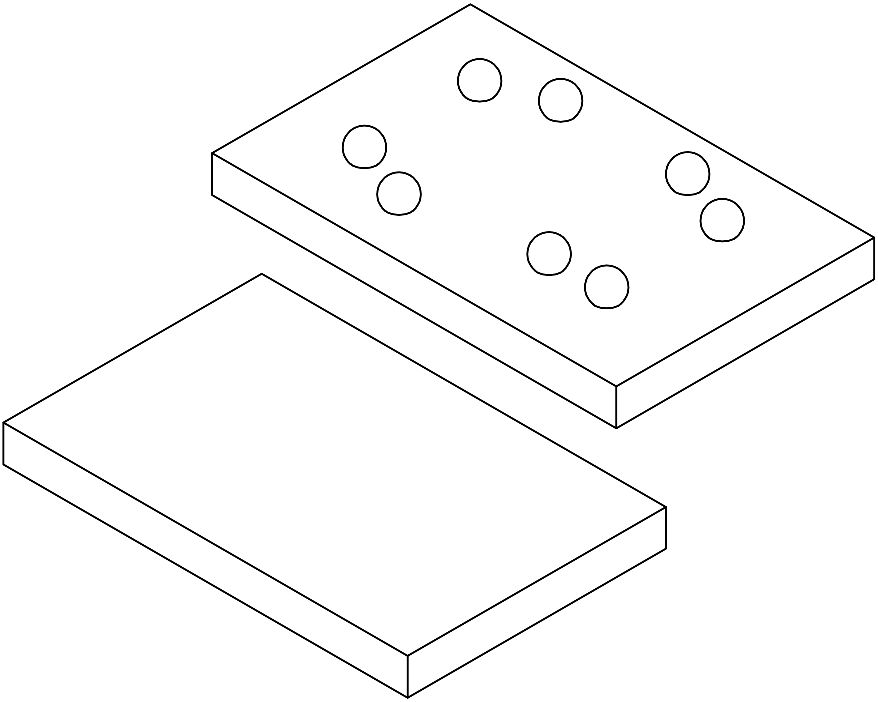
8-Ball Wafer Level Chip Scale Package (FEB) - [WLCSP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	8		
Ball Spacing	e	0.50 BSC		
Ball Spacing	e1	2.10 BSC		
Overall Height	A	0.456	0.495	0.534
Ball Height	A1	–	0.190	–
Die Thickness	A2	0.305 REF		
Overall Length	D	Contact Microchip for Details		
Ball Spacing	d1	1.00 BSC		
Ball Spacing	d2	1.40 BSC		
Overall Width	E	Contact Microchip for Details		
Ball Diameter	b	–	0.27	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.